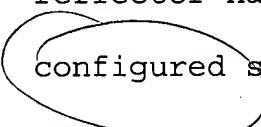
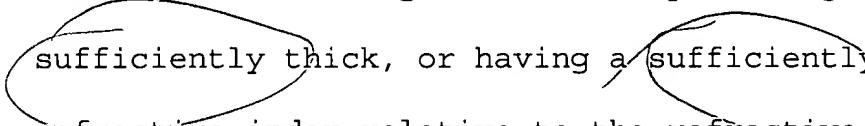


IN THE CLAIMS

Please cancel claims 22, 23, 26 and 30.

1. (Unchanged) An optoelectronic device having a top mirror and a bottom mirror, the top mirror and bottom mirror being at least partially conductive, the improvement comprising:

a resonant reflector positioned adjacent a selected one of the top or bottom mirrors, the resonant reflector having a waveguide and a grating  configured such that a first-diffraction order wave vector of the grating substantially matches a propagating mode of the waveguide; and

a cladding or buffer layer positioned between the resonant reflector and the selected top or bottom mirror, the cladding or buffer layer being sufficiently thick, or having a sufficiently low refractive index relative to the refractive index of the waveguide, to substantially prevent energy in the evanescent tail of the guided mode in the waveguide from entering the selected top or bottom mirror.

2. (Unchanged) An optoelectronic device according to claim 1, wherein cladding or buffer layer is non-

conductive.

3. (Unchanged) An optoelectronic device according to claim 1, wherein the cladding or buffer layer and the waveguide each have a refractive index, the refractive index of the cladding or buffer layer being substantially less than the refractive index of the waveguide.

4. (Unchanged) An optoelectronic device according to claim 3, wherein the selected top or bottom mirror includes an adjacent layer that is positioned adjacent the cladding or buffer layer, the refractive index of the cladding or buffer layer being less than the refractive index of the adjacent layer.

5. (Unchanged) An optoelectronic device according to claim 4, wherein the thickness of the cladding or buffer layer is thicker than the adjacent layer.

6. (Unchanged) An optoelectronic device according to claim 5, wherein the thickness of the cladding or buffer layer depends on the refractive index difference between the cladding or buffer layer and the waveguide.

7. (Unchanged) An optoelectronic device according to

claim 2, wherein the cladding or buffer layer is a dielectric film.

8. (Unchanged) An optoelectronic device according to claim 7, wherein the cladding or buffer layer is an aluminum oxide film.

9. (Unchanged) An optoelectronic device according to claim 7, wherein the waveguide region includes AlGaAs.

10. (Unchanged) An optoelectronic device according to claim 7, wherein the waveguide region includes a high refractive index dielectric.

11. (Unchanged) An optoelectronic device according to claim 7, wherein the grating is a dielectric film.

12. (Unchanged) An optoelectronic device according to claim 7, wherein the grating is a silicon oxide film.

13. (Unchanged) An optoelectronic device according to claim 7, wherein the cladding or buffer layer functions as part of the resonant reflector.

14. (Unchanged) A resonant reflector for an

optoelectronic device comprising:

a waveguide; and

a grating film having two or more spaced grating regions separated by one or more spaced regions, the spaced regions of the grating film having a grating film thickness that is less than the grating film thickness of the grating regions, but greater than the zero.

15. (Unchanged) A resonant reflector according to claim 14, wherein selected optical properties of the resonant reflector are controlled by the grating film thickness of the spaced regions and grating regions.

16. (Unchanged) A resonant reflector according to claim 15, wherein the spectral bandwidth of the resonant reflector is determined by the grating film thickness of the spaced regions and grating regions.

17. (Unchanged) A resonant reflector according to claim 15, wherein each grating region has a lateral width, with the grating regions collectively having a grating period, the grating period minus the grating width defining a grating spacing between adjacent grating regions, the

grating spacing divided by the grating period defining a grating fill factor, the grating fill factor being about 50%.

18. (Unchanged) A monolithic transceiver having a light emitting device and a light receiving device, comprising:

providing a bottom mirror on a substrate, the bottom mirror being at least partially conductive;

providing an active region on the bottom mirror;

providing a top mirror on the active region, the top mirror being at least partially conductive;

providing a cladding or buffer layer on the top mirror, the cladding or buffer layer being non-conductive;

providing a waveguide on the cladding or buffer layer;

providing a grating layer above the waveguide, the waveguide and grating being configured such that a first-diffraction order wave vector of the grating substantially matches a propagating mode of the waveguide;

the cladding or buffer layer being sufficiently thick, or having a sufficiently low refractive index relative to the refractive index of the waveguide, such that energy in the evanescent

tail of the guided mode in the waveguide is substantially prevented from entering the top mirror; and

the grating layer having a first etched grating structure above the light emitting device.

19. (Unchanged) A monolithic transceiver according to claim 18, further comprising a second etched grating structure above the light receiving device.

20. (Unchanged) A monolithic transceiver according to claim 18, wherein the grating layer does not have an etched grating structure above the light receiving device.

21. (Unchanged) A monolithic transceiver according to claim 18, wherein the grating layer is removed above the light receiving device.

22. (Canceled) A device comprising:
a first substrate having a front side and a back side with at least part of an optoelectronic device formed on the front side;
a second substrate having a front side and a back side with a resonant reflector formed on the front

side; and

the front side of the first substrate bonded to the
front side of the second substrate.

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23. (Canceled) A device according to claim 22, wherein
the resonant reflector includes a waveguide and a grating.

24. (Amended) A device according to claim 2345, wherein the
grating is positioned more toward the front side of the
second substrate than is the waveguide.

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25. (Amended) A device according to claim 2345, wherein the
waveguide is positioned more toward the front side of the
second substrate than is the grating.

26. (Canceled) A device according to claim 22, wherein
the front side of the first substrate is bonded to the
front side of the second substrate via an optical epoxy.

27. (Amended) A device according to claim 2646, wherein the
optical epoxy is non-conductive.

28. (Amended) A device according to claim 27, wherein the
waveguide and grating are configured such that a first-
diffraction order wave vector of the grating substantially
matches a propagating mode of the waveguide.

29. (Unchanged) A device according to claim 28, wherein

the optical epoxy is sufficiently thick, or has a sufficiently low refractive index relative to the refractive index of the waveguide, to substantially prevent energy in the evanescent tail of the guided mode in the waveguide from entering the first substrate.

30. (Canceled) A device according to claim 22, further comprising a collimating microlens positioned on the back side of the second substrate.

31. (Amended) A device according to claim 3047, wherein the collimating microlens is in registration with the resonant reflector and the optoelectronic device.

32. (Previously Canceled) A method for forming an optoelectronic device, comprising:

providing a bottom mirror on a substrate, the bottom mirror being at least partially conductive;

providing an active region above the bottom mirror;

providing a top mirror above the active region, the top mirror being at least partially conductive;

providing a cladding or buffer layer above the top mirror, the cladding or buffer layer being non-conductive; and

providing a waveguide and a grating above the cladding or buffer layer, the waveguide and grating configured such that a first-diffraction order wave vector of the grating substantially matches a propagating mode of the waveguide; and the cladding or buffer layer being sufficiently thick, or having a sufficiently low refractive index relative to the refractive index of the waveguide, to substantially prevent energy in the evanescent tail of the guided mode in the waveguide from entering the top mirror.

33. (Previously Canceled) A method according to claim 32, wherein the refractive index of the waveguide is higher than the average refractive index of the grating.

34. (Previously Canceled) A method according to claim 33 wherein the waveguide includes a first dielectric and the cladding or buffer layer includes a second dielectric layer, wherein the first dielectric has a higher refractive index than the second dielectric.

35. (Previously Canceled) A method according to claim 32, wherein the cladding or buffer layer is initially AlGaAs,

which is then oxidized to AlO.

36. (Previously Canceled) A method according to claim 35, wherein the cladding or buffer layer is laterally oxidized.

37. (Previously Canceled) A method according to claim 32, wherein the waveguide is formed from GaAs.

38. (Previously Canceled) A method according to claim 32, wherein the grating is formed by etching an SiO₂ film into a grating.

39. (Previously Canceled) A method according to claim 32, wherein the top mirror and bottom mirror are Distributed Bragg Reflector mirrors.

40. (Previously Canceled) A method according to claim 39, wherein the Distributed Bragg Reflector mirrors include alternating layers of AlGaAs and AlAs.

41. (Previously Canceled) A method according to claim 40, wherein a top layer of the top mirror is AlGaAs.

42. (Previously Canceled) A method for forming a resonant reflector for an optoelectronic device comprising:

providing a waveguide;
providing a grating film adjacent the waveguide; and
etching the grating film to form two or more spaced
grating regions separated by one or more spaced
etched regions, the etched regions extending to a
depth that produces a desired optical property
for the resonant reflector but not extending all
the way through the grating film.

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43. (Previously Canceled) A method according to claim 42,
wherein the depth of the etched regions is selected to
produce a desired bandwidth for the resonant reflector.

44. (Previously Canceled) A method according to claim 42,
wherein the two or more spaced grating regions have a
grating period, the grating period selected to produce a
desired resonant wavelength for the resonant reflector.

45. (New) A device comprising:
a first substrate having a front side and a back side
with at least part of an optoelectronic device
formed on the front side;
a second substrate having a front side and a back side
with a resonant reflector formed on the front
side; and

the front side of the first substrate bonded to the front side of the second substrate; and wherein the resonant reflector includes a waveguide and a grating.

46. (New) A device comprising:

a first substrate having a front side and a back side with at least part of an optoelectronic device formed on the front side;

a second substrate having a front side and a back side with a resonant reflector formed on the front side; and

the front side of the first substrate bonded to the front side of the second substrate; and

wherein the front side of the first substrate is bonded to the front side of the second substrate via an optical epoxy.

47. (New) A device comprising:

a first substrate having a front side and a back side with at least part of an optoelectronic device formed on the front side;

a second substrate having a front side and a back side with a resonant reflector formed on the front side;

the front side of the first substrate bonded to the front side of the second substrate; and

a collimating microlens positioned on the back side of

the second substrate.

48. (New) A device comprising:

a first substrate having a front side and a back side
with at least part of an optoelectronic device
formed on the front side;

a second substrate having a front side and a back side
with a resonant reflector formed on the front
side; and

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the front side of the first substrate bonded to the
front side of the second substrate; and
wherein the resonant reflector includes a grating.

49. (New) A device comprising:

a first substrate having a front side and a back side
with at least part of an optoelectronic device
formed on the front side;

a second substrate having a front side and a back side
with a resonant reflector formed on the front
side; and

the front side of the first substrate bonded to the
front side of the second substrate; and
wherein the resonant reflector includes a waveguide.